

**• General Description**

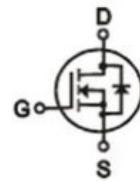
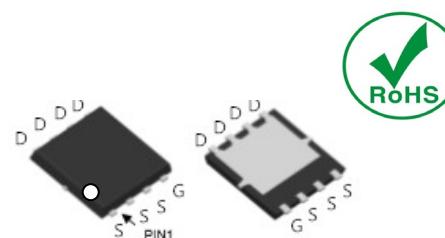
The ZM016N04HN combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

**• Features**

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

**• Application**

- Synchronous Rectification for AC-DC/DC-DC converter
- BLDC Motor driver

**• Product Summary** $V_{DS}=40V$  $R_{DS(ON)}=1.55m\Omega$  $I_D=220A$ 

DFN5 x 6

**• Ordering Information:**

Part NO.	ZM016N04HNC
Marking	ZM016N04H
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

**• Absolute Maximum Ratings ( $T_c = 25^\circ C$ )**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D@T_c=25^\circ C$	220	A
	$I_D@T_c=75^\circ C$	165	A
	$I_D@T_c=100^\circ C$	138	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	660	A
Total Power Dissipation	$P_D@T_c=25^\circ C$	85	W
Total Power Dissipation	$P_D@T_A=25^\circ C$	3.4	W
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ C$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy@L=0.5mH	$E_{AS}$	1150	mJ



Single Pulse Avalanche Energy@L=0.1mH	E <sub>AS</sub>	460	mJ
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### •Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	1.5	° C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	37	° C/W
Soldering temperature, wave soldering for 10s	T <sub>sold</sub>	-	-	265	° C

### •Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	40			V
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2.0		4.0	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V			1.0	uA
Gate- Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
Static Drain-source On Resistance	R <sub>D(S)ON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =40A		1.55	2.1	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =25V, I <sub>D</sub> =10A		25		s
Source-drain voltage	V <sub>SD</sub>	I <sub>S</sub> =40A			1.28	V

### •Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =20V f = 1MHz	-	6610	-	pF
Output capacitance	C <sub>oss</sub>		-	460	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	210	-	

### •Gate Charge characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Gate Resistance	R <sub>g</sub>	f = 1MHz		2.5		Ω
Total gate charge	Q <sub>g</sub>	V <sub>DD</sub> = 20V I <sub>D</sub> = 25A V <sub>GS</sub> = 10V	-	109	-	nC
Gate - Source charge	Q <sub>gs</sub>		-	18	-	
Gate - Drain charge	Q <sub>gd</sub>		-	21	-	
Turn-ON Delay time	t <sub>D(on)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V		12		ns



Turn-ON Rise time	$t_r$	$R_G = 3.3\Omega$ , $I_D = 25A$	14		ns
Turn-Off Delay time	$t_{D(off)}$		89		ns
Turn-Off Fall time	$t_f$		34		ns
Reverse Recovery Time	$t_{RR}$	VDD = 20 V, $dI/dt=100A/\mu s$ , $I_S = 30 A$	25		ns
Charge Time	$t_a$		14		ns
Discharge Time	$t_b$		11		ns
Reverse Recovery Charge	$Q_{RR}$		16		ns

Note: ① Pulse Test : Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$  ;

Fig.1 Gate-Charge Characteristics

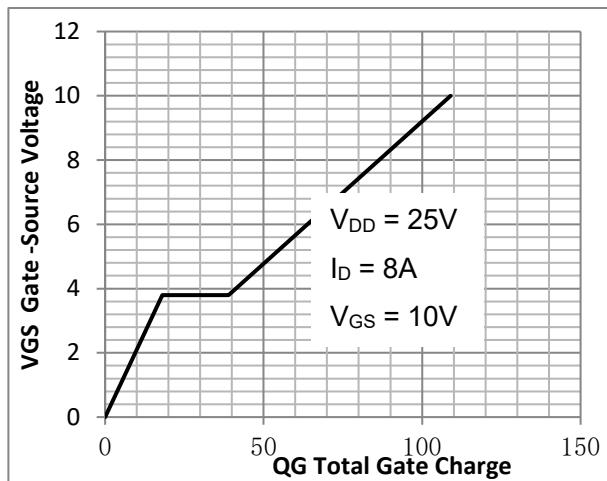


Fig.2 Capacitance Characteristics

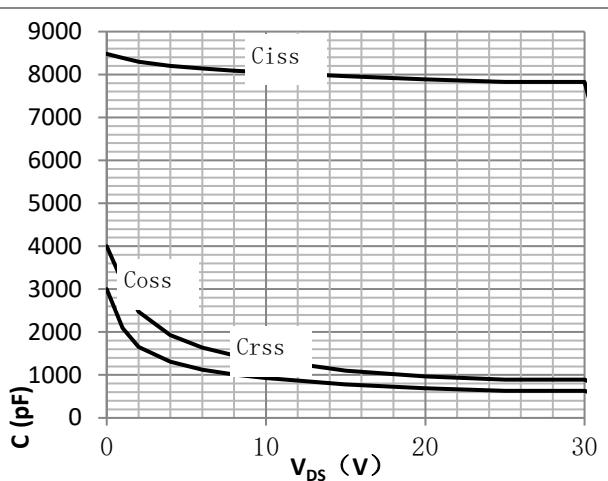


Fig.3 Power Dissipation

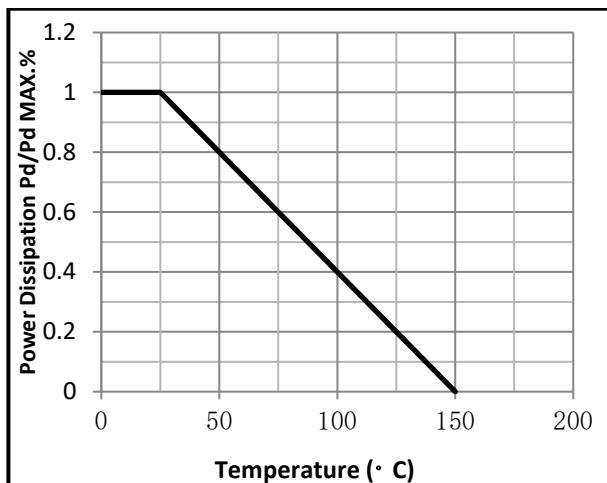


Fig.4 Typical output Characteristics

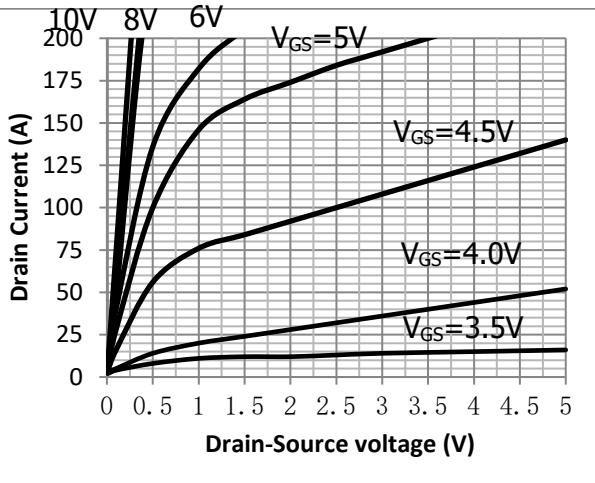




Fig.5 Threshold Voltage V.S Junction Temperature   Fig.6 Resistance V.S Drain Current

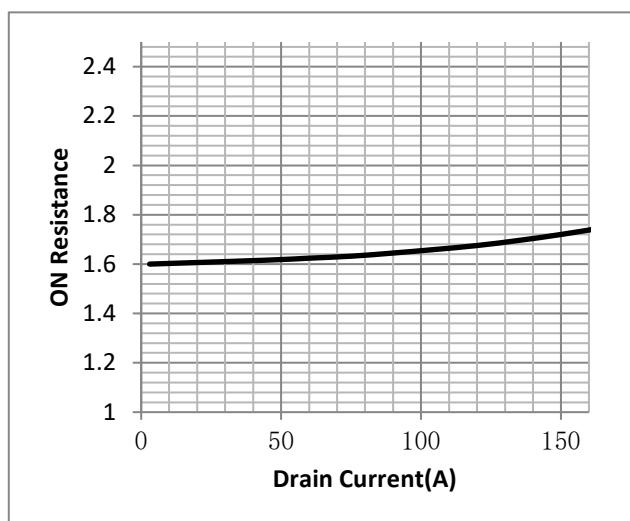
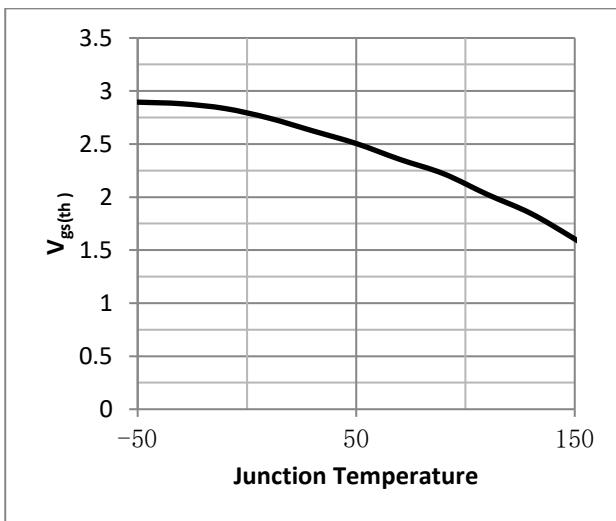


Fig.7 On-Resistance VS Gate Source Voltage

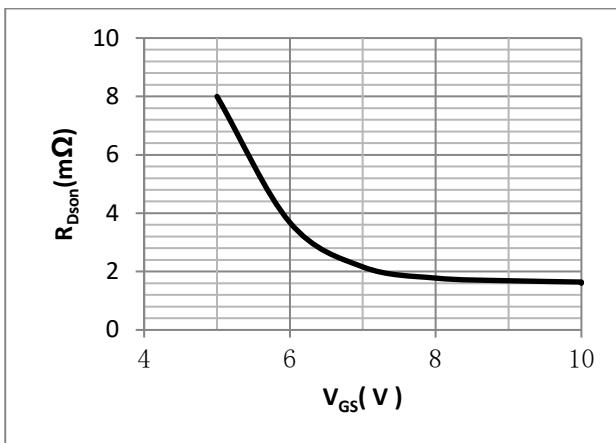


Fig.8 On-Resistance V.S Junction Temperature

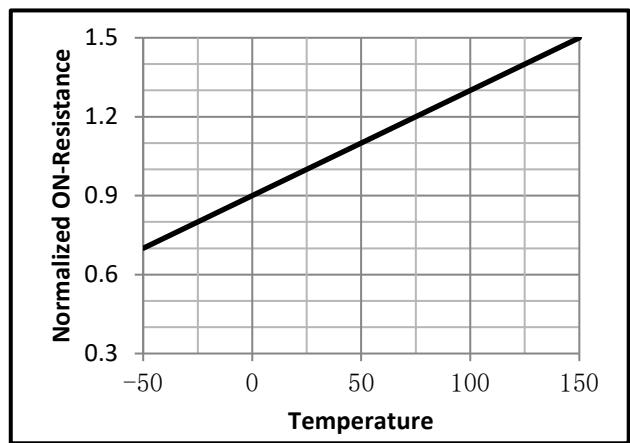


Figure 9. Diode Forward Voltage vs. Current

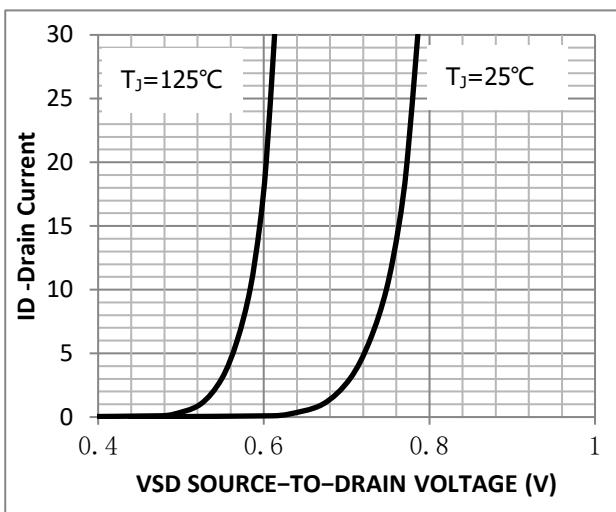


Figure 10. Transfer Characteristics

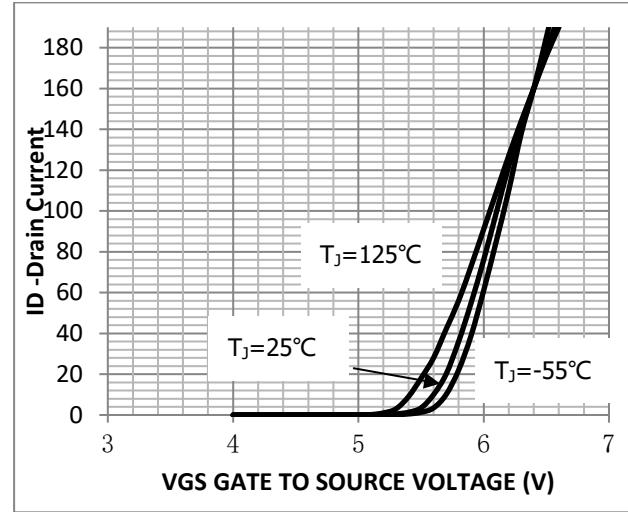




Fig.11 SOA Maximum Safe Operating Area

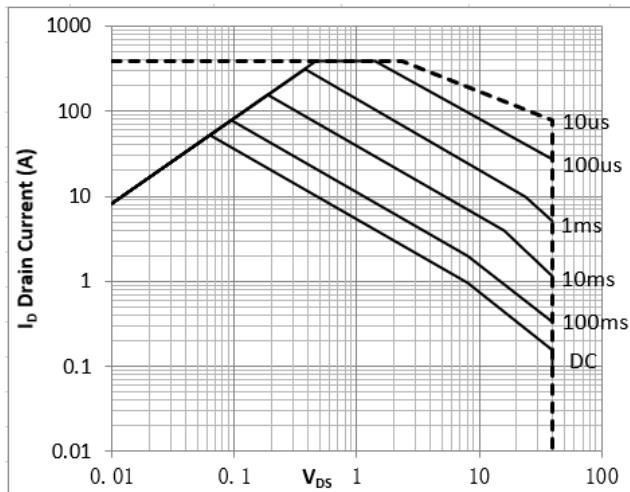


Fig.12 ID-Junction V.S Temperature

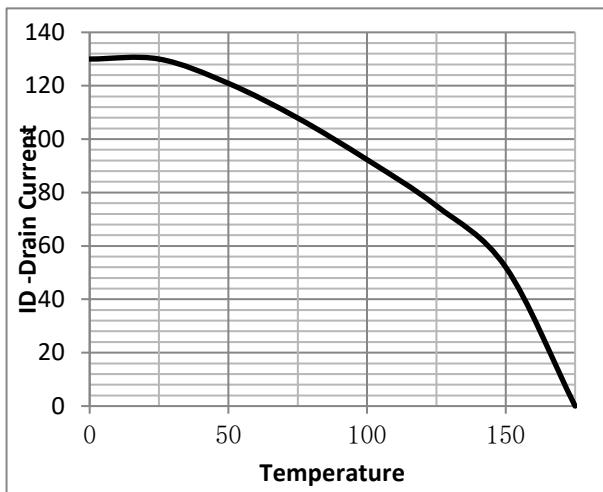


Fig.12 Switching Time Measurement Circuit

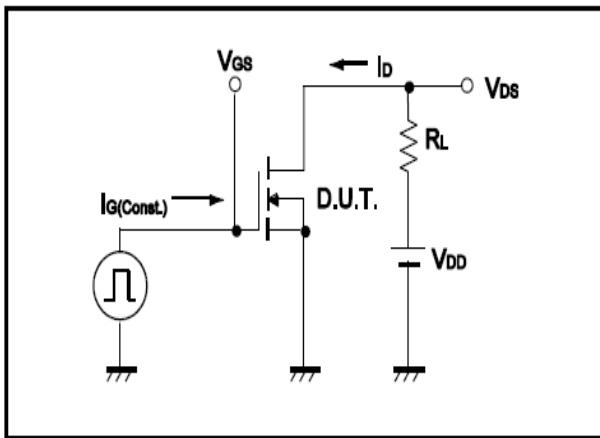


Fig.14 Gate Charge Waveform

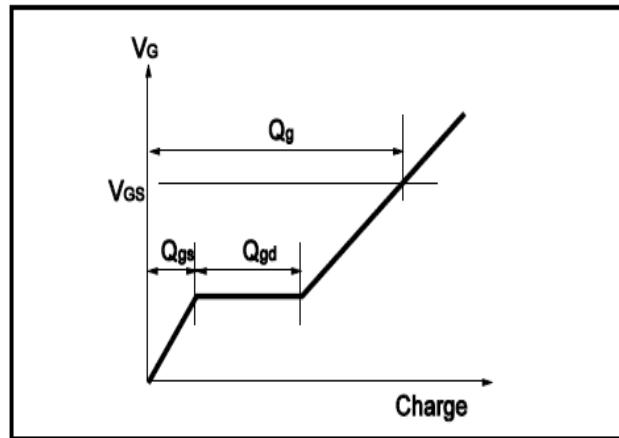


Fig.15 Switching Time Measurement Circuit

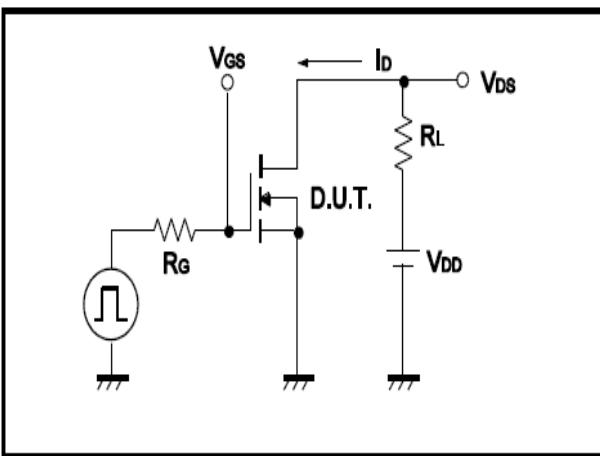
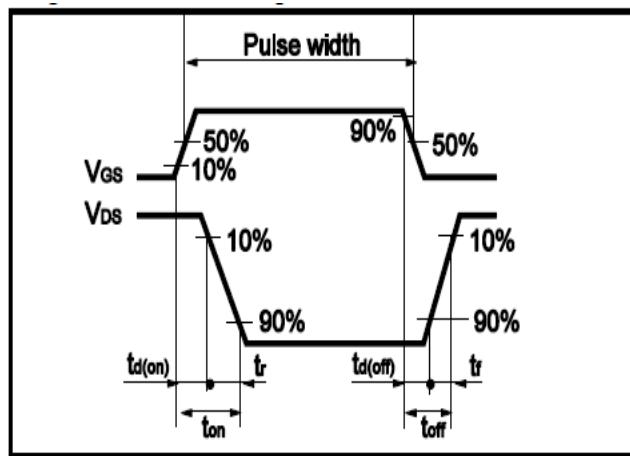


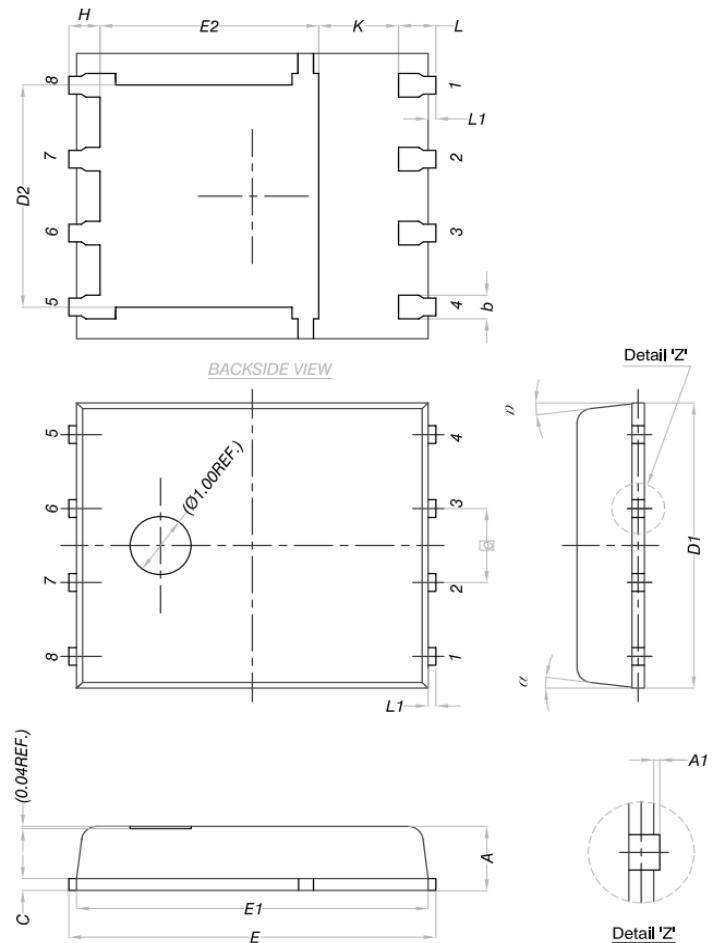
Fig.16 Gate Charge Waveform





## •Dimensions (DFN5x6)

Unit: mm



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	0°	-	12°